

**AMENDMENTS TO THE CLAIMS**

**This listing of claims will replace all prior versions and listings of claims in the application:**

**LISTING OF CLAIMS:**

1. - 4. (canceled).

5. (currently amended): A powdered resin composition for slush molding comprising a thermoplastic polyurethane resin powder (B) as the main component and a fine particle powder (E) of a vinyl type copolymer comprising a copolymer of an alkyl (meth)acrylate and a hydroxyl-containing vinyl type monomer and having a cross-linked structure as a powder flowability improver, wherein the fine particle powder (E) is not melted in the temperature range of 200 to 300°C, the resin powder (B) has a volume average particle diameter in a range from 70 to 300 µm and is capable of melting at 200 to 300°C, and the thermoplastic polyurethane resin powder (B) and the fine particle powder are dry-blended at room temperature, wherein the fine particle powder (E) of a vinyl type copolymer is contained in an amount from 0.1% by weight to 1.5% by weight to the thermoplastic polyurethane resin powder (B).

6. (previously presented): The powdered resin composition according to claim 5, wherein the fine particle powder (E) of a vinyl type copolymer is a copolymer of methyl (meth)acrylate and hydroxyethyl (meth)acrylate.

7. (previously presented): The powdered resin composition according to claim 5, wherein the fine particle powder (E) of a vinyl type copolymer has a cross-linked structure formed by crosslinking a hydroxyl group with an organic polyisocyanate.

8. - 14. (canceled).

15. (previously presented): The powdered resin composition according to claim 6, wherein the fine particle powder (E) of a vinyl type copolymer has a cross-linked structure formed by crosslinking a hydroxyl group with an organic polyisocyanate.

16. (previously presented): The powdered resin composition according to claim 5 further containing a silica fine powder.

17. (previously presented): The powdered resin composition according to claim 5, wherein the fine particle powder (E) of a vinyl type copolymer has a volume average particle diameter in a range from 0.1  $\mu\text{m}$  to 100  $\mu\text{m}$ .

18. (canceled).

19. (previously presented): The powdered resin composition according to claim 5 being obtained by dry-blending the thermoplastic polyurethane resin powder (B) with the fine particle powder (E) of a vinyl type copolymer together with an additive (D) to be added.

20. (previously presented): A urethane resin molded product produced from the powdered resin composition for slush molding according to claim 5.

21. (new): The powdered resin composition according to claim 17, wherein the fine particle powder (E) of a vinyl type copolymer has a volume average particle diameter in a range from 3  $\mu\text{m}$  to 5  $\mu\text{m}$ .

22. (new): A method for producing a powdered resin composition for slush molding, comprising:

preparing a thermoplastic polyurethane resin powder (B) as the main component and a fine particle powder (E) of a vinyl type copolymer comprising a copolymer of an alkyl (meth)acrylate and a hydroxyl-containing vinyl type monomer and having a cross-linked structure as a powder flowability improver, wherein the fine particle powder (E) is not melted in the temperature range of 200 to 300°C, the resin powder (B) has a volume average particle diameter in a range from 70 to 300  $\mu\text{m}$  and is capable of melting at 200 to 300°C, wherein the fine particle powder (E) of a vinyl type copolymer is contained in an amount from 0.1% by weight to 1.5% by weight to the thermoplastic polyurethane resin powder (B); and

dry-blending the thermoplastic polyurethane resin powder (B) and the fine particle powder (E).

23. (new): The method for producing a powdered resin composition for slush molding according to claim 22, wherein dry-blending is performed at room temperature.

24. (new): The method for producing a powdered resin composition for slush molding according to claim 22, the fine particle powder (E) of a vinyl type copolymer has a volume average particle diameter in a range from 3  $\mu\text{m}$  to 5  $\mu\text{m}$ .